



PATENT

#15/C
Heener
7/21/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: 3326

Examiner: M. Trinh

Group Art Unit: 2822

Attorney Docket No.: 3572.1US
(97-1243.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

July 7, 2003
Date

Signature

Leah Barrow

Name (Type/Print)

AMENDMENT

Mail Stop NON-FEE AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed May 8, 2003, the three-month shortened statutory period for response to which expires on August 8, 2003.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

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